



深圳市格天光电有限公司
Shenzhen Getian Opto-Electronics Co., Ltd

产品规格书

The product specification

CUSTOMER/客户名称: _____

MODEL NO./产品型号: _____ GT-P04Y2410360

DESCRIPTION/产品描述: _____ 3W黄光

SAMPLE DATE/送样日期: _____

CUSTOMER AUTHORIZED SIGNATURE/客户承认签核

Please return to us a copy of "APPROVAL SHEET" after customer
Signature./客户签字确认，盖章后请回传一份承认书至我司。

| engineering department 工程部 | | |
|-------------------------------|-----------------|-----------------|
| APPROVED (核准) | CHECKED (审核) | DRAW UP (制定) |
| | | |

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GT-POWER LED Series

Technical Datasheet for GT-03/04

GETIAN SEMICONDUCTOR

只做大功率



GT-Power series is designed for high current operation and high flux output applications.

GT-Power LED its thermal management perform exceeds then other power LED solutions.

It integrate of the art SMD design and thermal emission material.

GT-Power LED is ideal light sources for general applications, custom designed solutions, and automotive large LCD backlights.

Features

- *Super high Flux output and high Luminance
- *Designed for high current operation
- *Low thermal resistance
- *SMT solder bility
- *Lead Free product
- *ROHS compliant

Applications

- *General Illumination
 - Outdoor & Indoor architectural lighting
 - Decorative lighting
 - Torch lighting
 - Portable lighting and Reading lighting
 - Traffic signaling

Full Code of GT-Power LED Series

| | | | | | | | | | | |
|-----------------|-----------|---|----------|-----------|-----------|----------|----------|----------|----------|-----------|
| Full code form: | <u>GT</u> | - | <u>P</u> | <u>XX</u> | <u>XX</u> | <u>X</u> | <u>X</u> | <u>X</u> | <u>X</u> | <u>XX</u> |
| | 1 | | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 |
| | GT | | P | 04 | Y2 | 4 | 1 | 0 | 3 | 60 |

Part Number

1- GT: GeTi an

2- P : High Power LED

3- XX: Part sort

03: With baseplate 04: Without baseplate

4- XX: Emitted Color

R1 - Red 625nm B3 - Blue 465nm Y2 - Yellow 590nm

5- X : Wafer Size

2 - 24mil 3 - 30mil 4 - 45mil 5-50mil 6 - 60mil

6- X : Wafer Quantity

1 - 1EA 4 - 4EA

7- X : Viewing Angle

0 - 120deg 1 - 15deg

8- X : Power

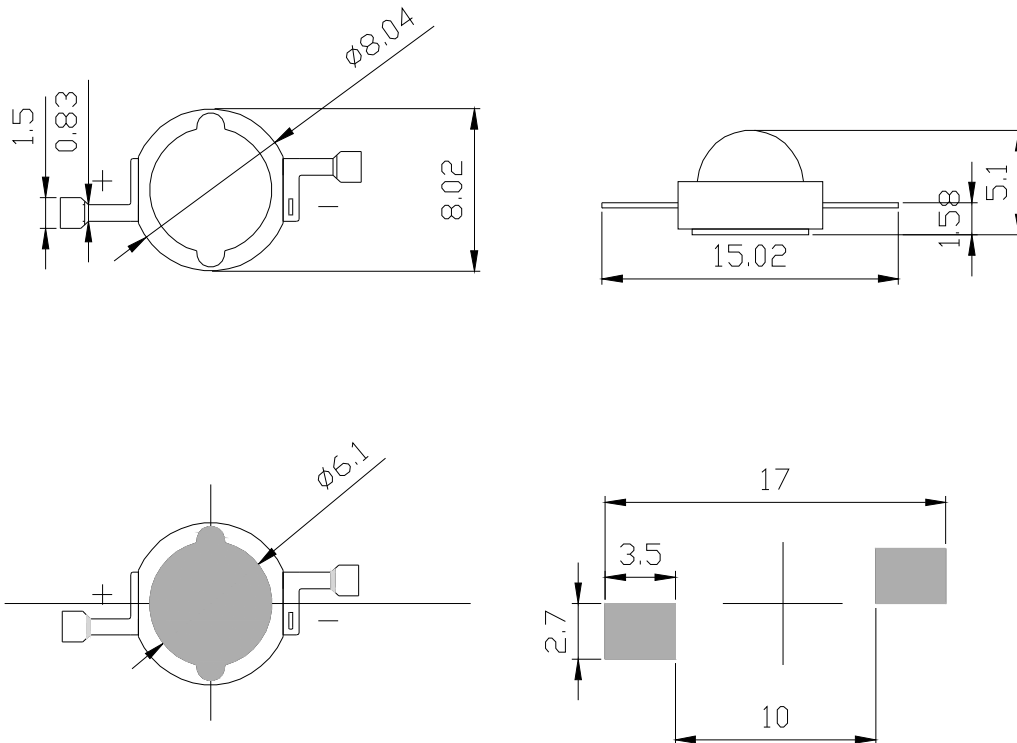
0 - 0.5W 1 - 1W 3 - 3W

9- XX: Brightness Grade

40 - 40-50lm 60 - 60-80lm

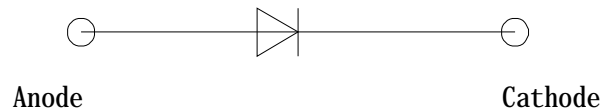
Outline Dimensions

1、 Dome Type



2、 Circuit diagram

[INTERNAL CIRCUIT DIAGRAM]



Notes

1. All dimensions are in millimeters.(tolerance:±0.2)
2. Scale:none

*the appearance and specifications of the product may be changed for improvment without notice.

Characteristics for GT-P04Y2410360
1、 Neutral -White

1-1 Electrical-Optical Characteristics at IF=800mA, TA=25℃

| Parameter | Symbol | Value | | | Unit |
|-----------------------------------|-------------------------|-------|-----|-----|------|
| | | Min | Typ | Max | |
| Luminous Flux ^[1] | ϕ_v ^[2] | 60 | ~ | 80 | lm |
| Wavelength ^[3] | ~ | 588 | ~ | 593 | nm |
| Forward Voltage ^[4] | V _F | 2.2 | ~ | 2.8 | V |
| View Angle | 2θ1/2 | 120 | | | deg. |
| Thermal Resistance ^[5] | R _{θ J-B} | 8 | | | ℃/W |
| Thermal Resistance ^[6] | R _{θ J-C} | 6.5 | | | ℃/W |

1-2 Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit |
|--------------------------------|------------------|-------------|------|
| Forward Current | I _F | 800 | mA |
| Power Dissipation | P _D | 3 | W |
| Junction Temperature | T _j | 120 | ℃ |
| Operating Temperature | T _{opr} | -30~+85 | ℃ |
| Storage Temperature | T _{stg} | -40~+120 | ℃ |
| ESD Sensitivity ^[7] | ~ | ±2,000V HBM | ~ |

*Notes:

[1] SSC maintains a tolerance of ±10% on flux and power measurements.

 [2] ϕ_v is the total luminous flux output as measured with an integrated sphere.

[3] Correlated Color Temperatures is derived from the CIE 1931 Chromaticity diagram.

CCT ±5% testing tolerance

[4] A tolerance of ±0.06V on forward voltage measurements

 [5] ,[6] R_{θ J-B} is measured with a SSC metal core pcb.(25℃ ≤ T_J ≤ 110℃)

 R_{θ J-C} is measured with only emitter.. (25℃ ≤ T_J ≤ 110℃)

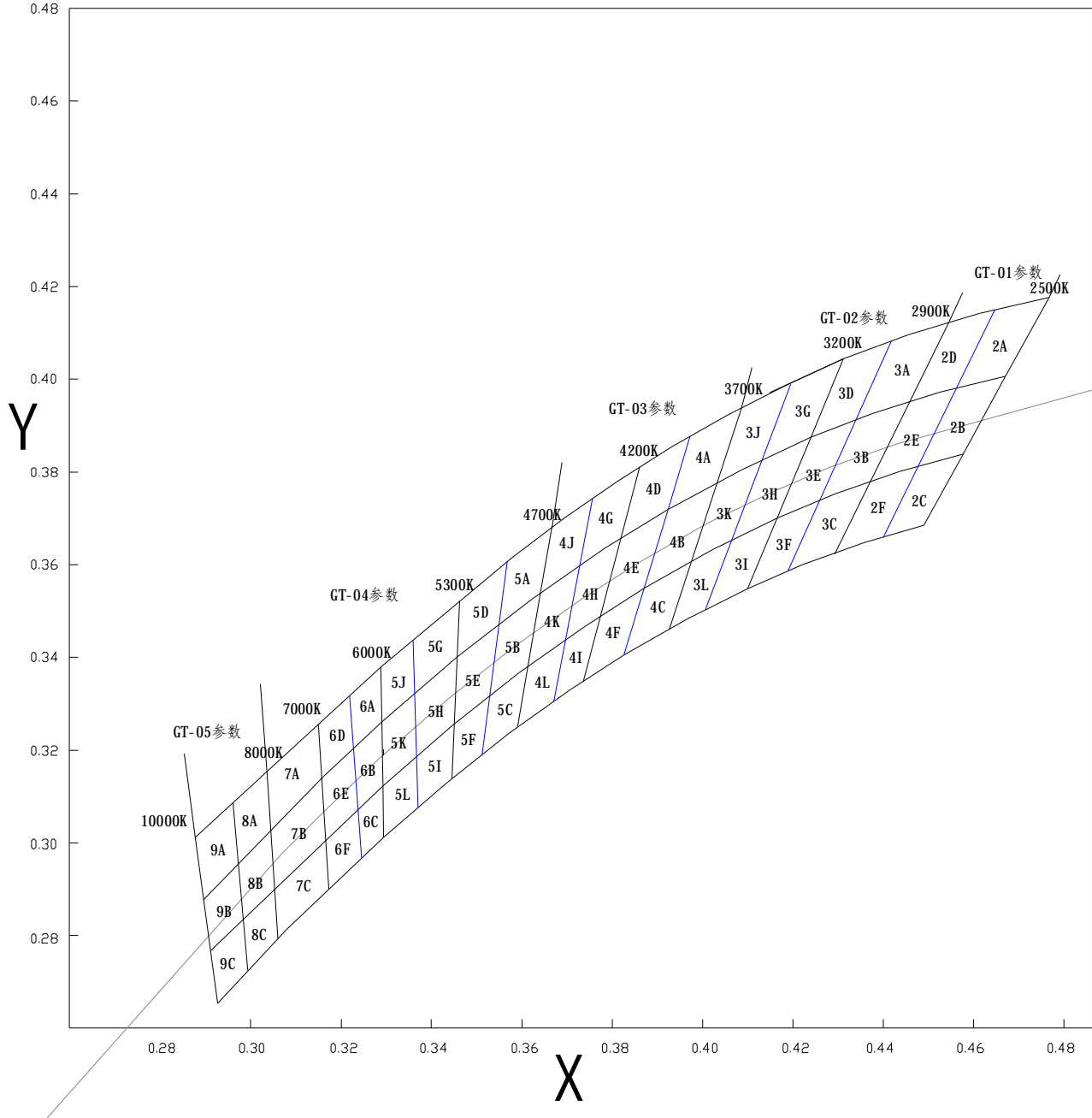
Break voltage of Metal PCB is 6.5kVAC

[7]It is included the zener chip to protect the product from ESD.

-----**Caution**-----

Please do not drive at rated current more than 5sec. Without proper heat sink

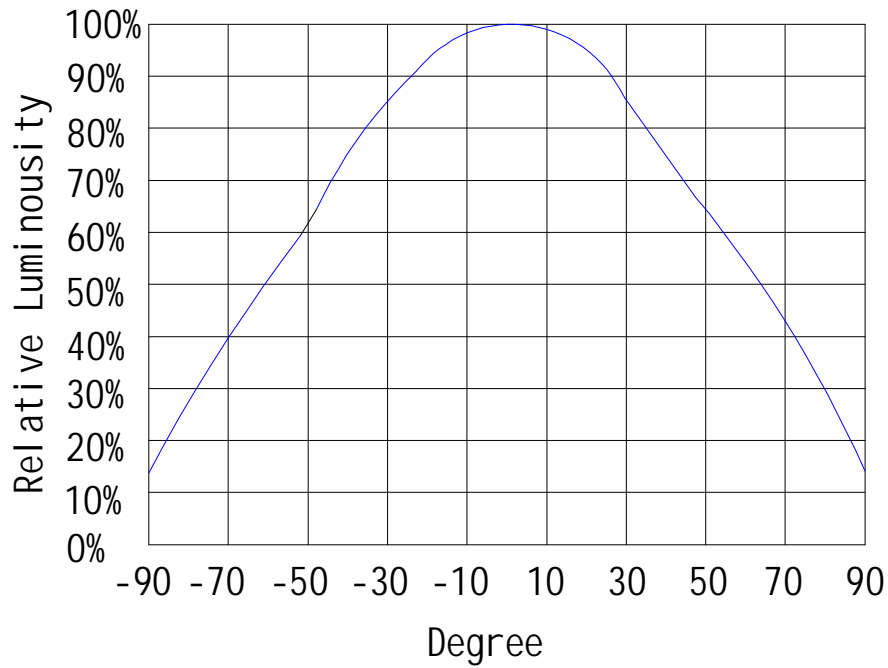
White Binning Information



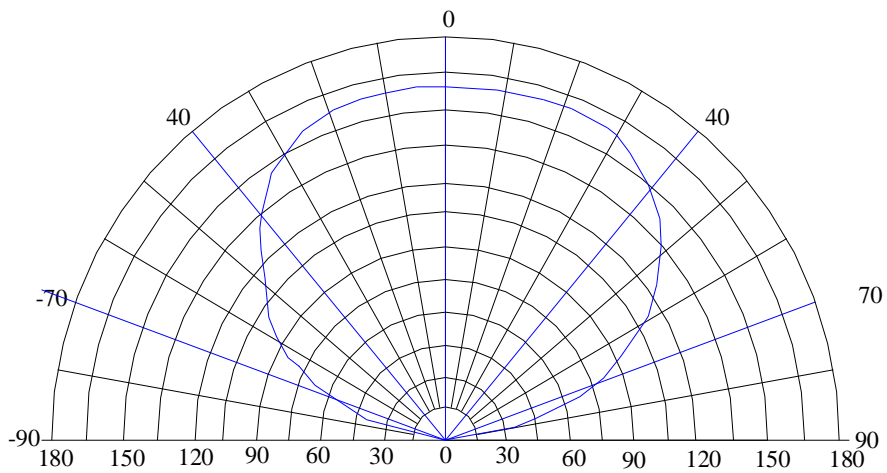
White Binning Sluze

| Division of BIN code and sample BIN code for white light | | | | |
|--|--------------------------------|------------------|---------------------------|----------------------------|
| BIN code | Color Temperature Range | | Center Value | Sample BIN Code |
| 2A/2B/2C/2D/2E/2F | 2500-2900K | | 2700K | 2E |
| 3A/3B/3C/3D/3E/3F | 2900-3200K | | 3000K | 3B |
| 3G/3H/3I/3J/3K/3L | 3200-3700K | | 3500K | 3H |
| 4A/4B/4C/4D/4E/4F | 3700-4200K | | 4000K | 4E |
| 4G/4H/4I/4J/4K/4L | 4200-4700K | | 4500K | 4H |
| 5A/5B/5C/5D/5E/5F | 4700-5300K | | 5000K | 5B |
| 5G/5H/5I/5J/5K/5L | 5300-6000K | | 5700K | 5K |
| 6A/6B/6C/6D/6E/6F | 6000-7000K | | 6500K | 6B |
| 7A/7B/7C | 7000-8000K | | 7500K | 7B |
| 8A/8B/8C/9A/9B/9C | 8000-10000K | | 9000K | 8B |
| 1.The division of luminous flux for white light is 10LM per grade | | | | |
| 2.The division of voltage for white light is 0.2V Per grade | | | | |
| BIN Division Standard Of Red,Green,Blue | | | | |
| Wavelength | Color | Lumen | Voltage(0.2V/each) | Total Amount of BIN |
| 615-630 (2.5nm/each) | Red | 10LM/each | 2.0-2.6 | 36 |
| 515-530 (2.5nm/each) | Green | 10LM/each | 3.0-3.6 | 36 |
| 455-470 (2.5nm/each) | Blue | 10LM/each | 3.0-3.6 | 36 |

1、Typical Radiatiation Patterns

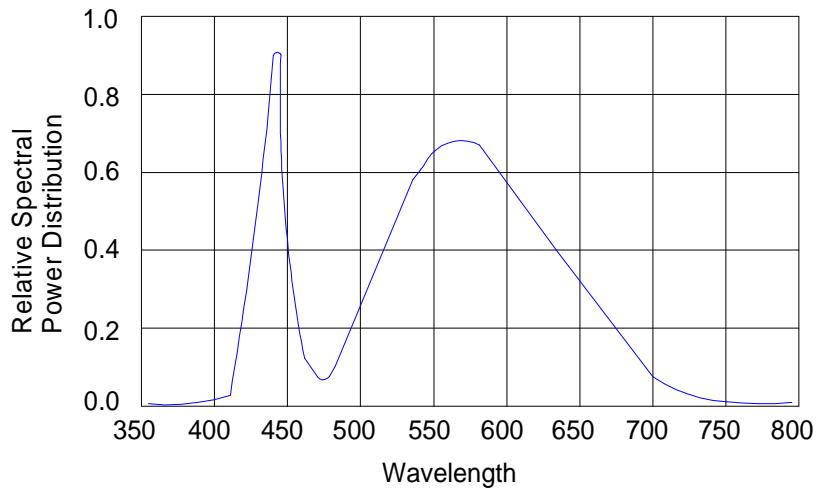


2、Typical representative Spatial Radiation Pattern

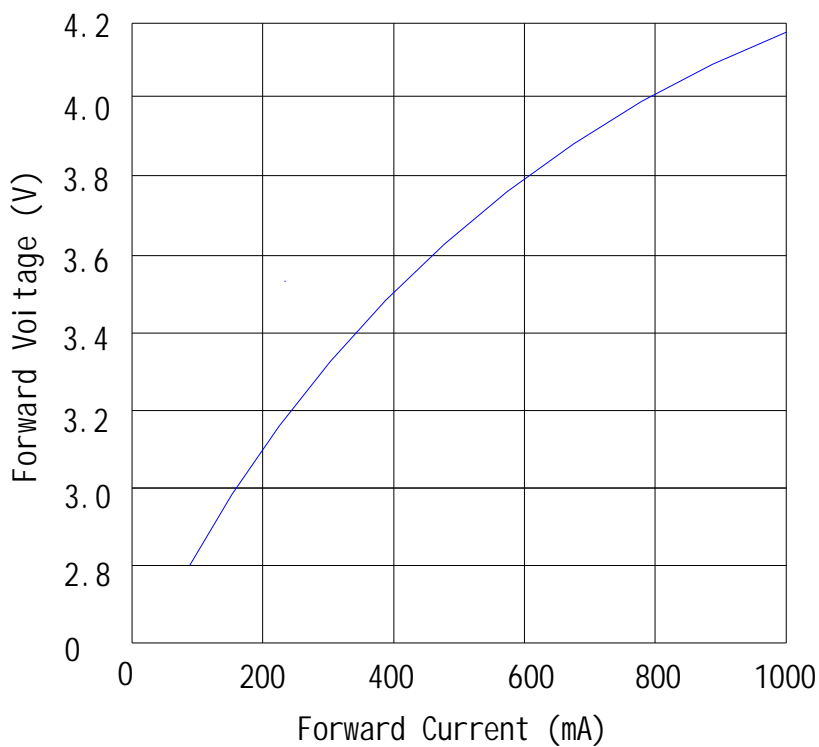


Typical Polar Radiation Pattern for White Lambertian

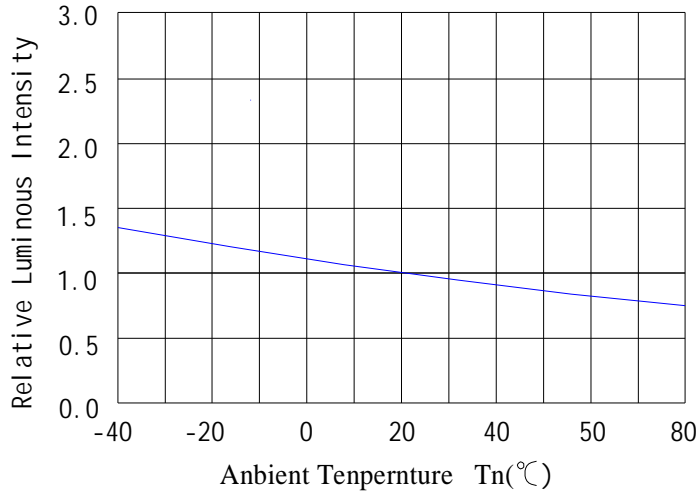
3、Neutral-White color spectrum of typical CCT part, integrated measurement



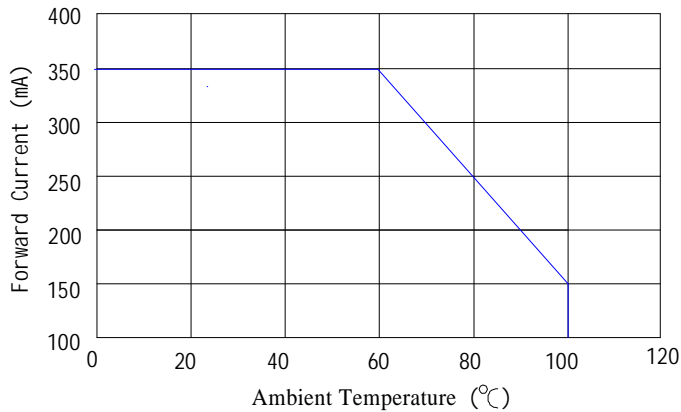
4、Forward Current vs. Forward Voltage



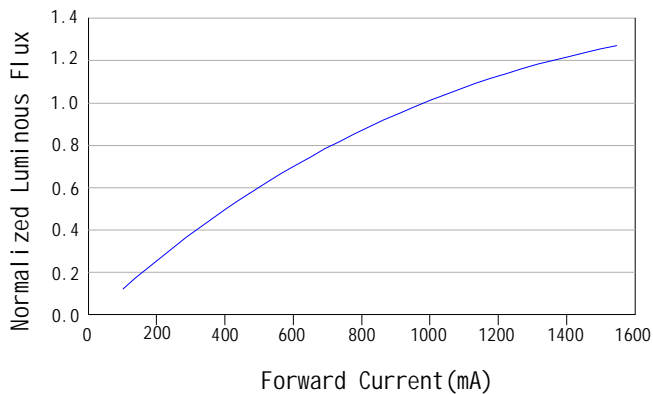
5、Relative Luminous Intensity vs. Ambient Temperature



6、Forward Current Derting Curve, Derting based on $T_{i\max}=125^\circ\text{C}$



7、Relative Luminous Flux vs. Forward Current



Test Items And Condition

| Items | Test Condition | Test Hours Cycles | Sample Size | Ac/Re |
|--------------------------------|-------------------------------|-------------------|-------------|-------|
| DC Operating Life | Ta=25°C IF=1000mA | 1000H | 22 | 0/1 |
| Reflow Soldering | Temp 210°C ± 5°C 5sec. min | 1Time | 22 | 0/1 |
| Thermal Shock | -40°C/30min +100°C/30min | 50Cycles | 22 | 0/1 |
| High Temperature Storage | 100°C | 168H | 22 | 0/1 |
| High Temperature High Humidity | 85°C/85%RH | 168H | 22 | 0/1 |
| Low Temperature Storage | -40°C | 168H | 22 | 0/1 |
| ESD(HBM) | 2000V HBN | 1Time | 10 | 0/1 |

Criteria For Judging the Damage

| Items | Symbol | Limit | | Test Condition |
|--------------------|--------|-----------|-----------|----------------|
| | | L. S. | U. S. | |
| Luminous Intensity | IV | L. S. L08 | — | IF=800mA |
| Forward Voltage | VF | — | L. S. 1.1 | IF=800mA |
| Reverse Current | IR | — | L. S. 2.0 | VR=5V |

Note:

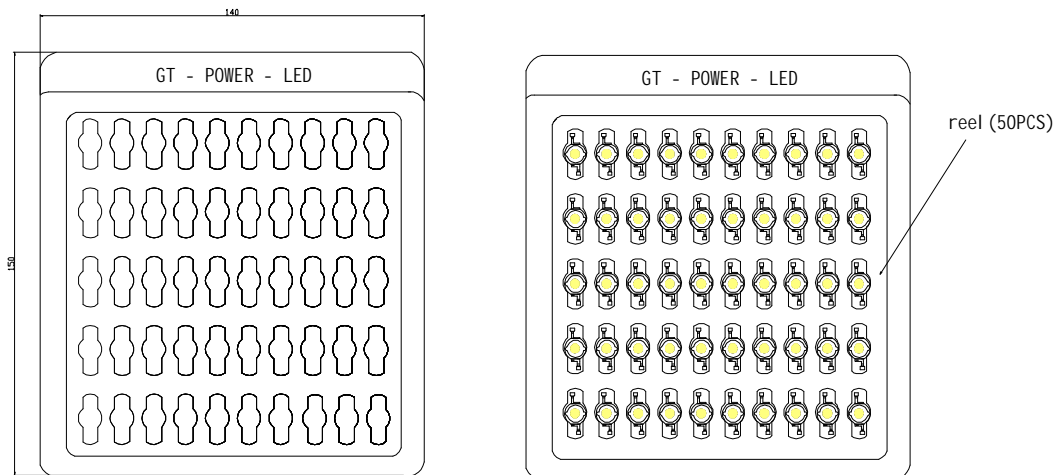
L. S. L: Lower Standard Level

U. S. L: Upper Standard Level

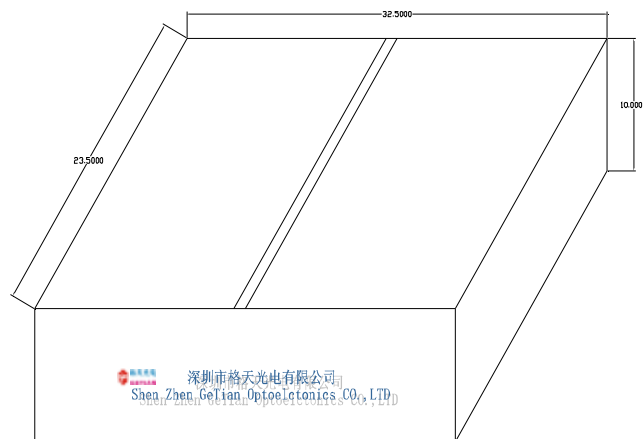
Soldering Condition

| Reflow-Soldering | | | Manual Welding |
|-----------------------------|------------|------------------|---------------------------|
| | Beadsolder | Lead-free solder | Temperature |
| Preheat | 120-150°C | 180-200°C | Soldering time |
| Heatup time | 120Sec Max | 120Sec Max | |
| Peak temperature | 240°C Max | 260°C Max | highest 260°C 3seconds |
| Condition of Soldering time | 10Secs Max | 10Secs Max | Disposable devices |

Packing Dimension



inner pack



Outer pack